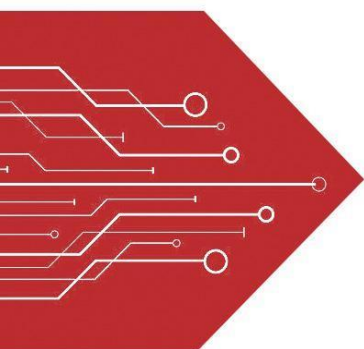
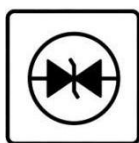


MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV

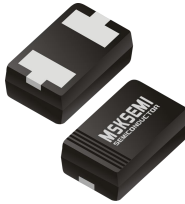


GDT



PLED

Product data sheet



DFN1006

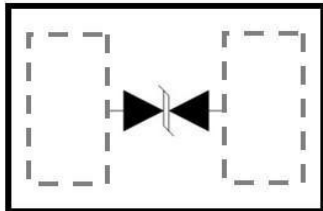
FEATURES

- ✧ IEC61000-4-2 (ESD) $\pm 8\text{kV}$ (Contact)
 $\pm 15\text{kV}$ (Air)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (Lighting) 3A (8/20 μs)
- ✧ 100 Watts Peak Pulse Power (tp=8/20 μs)
- ✧ Working voltages : 24V
- ✧ Low clamping voltage
- ✧ Low leakage current

MACHANICAL DATA

- ✧ DFN1006 package
- ✧ Flammability Rating: UL 94V-0
- ✧ Packaging: Tape and Reel
- ✧ Reel size: 7 inch

PIN CONFIGURATION



APPLICATIONS

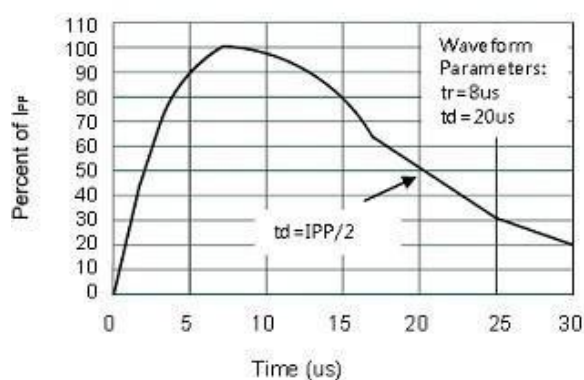
- ✧ Serial and Parallel Ports
- ✧ Notebooks, Desktops, Servers
- ✧ Projection TV
- ✧ Cellular handsets and accessories
- ✧ Portable instrumentation
- ✧ Peripherals

ABSOLUTE MAXIMUM RATING

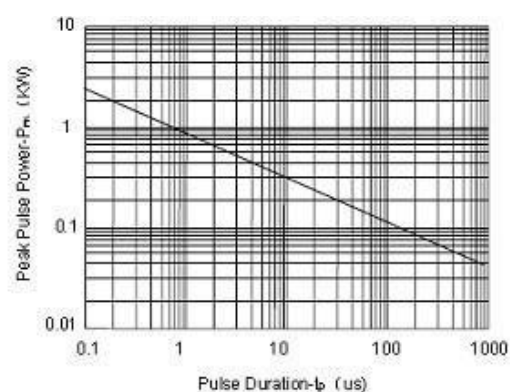
Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Contact)	± 8	kV
	ESD per IEC 61000-4-2 (Air)	± 15	
P_{PP}	Peak Pulse Power (8/20 μs)	150	W
T_{OPT}	Operating Temperature	-55 ~ +125	$^{\circ}\text{C}$
T_{STG}	Storage Temperature	-55 ~ +150	$^{\circ}\text{C}$
T_{L}	Lead Soldering Temperature	260 (10 sec.)	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS (T _{amb} =25°C)						
Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V _{RWM}	Reverse Working Voltage				24	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA	26		32	V
I _R	Reverse Leakage Current	V _{RWM} = 24V			1	μA
V _{C1}	Clamping Voltage 1	I _{PP} = 1A, t _p = 8/20μs			40	V
V _{C2}	Clamping Voltage 2	I _{PP} = 3A, t _p = 8/20μs			50	V
C _J	Junction Capacitance	V _R = 0V, f = 1MHz		8		pF

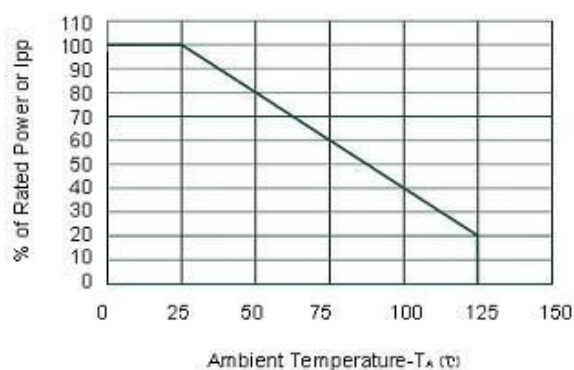
ELECTRICAL CHARACTERISTICS CURVE



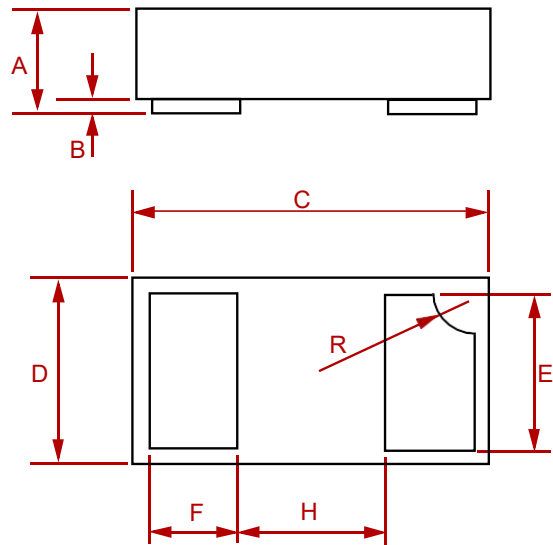
Pulse Waveform



Non-Repetitive Peak Pulse Power vs. Pulse Time

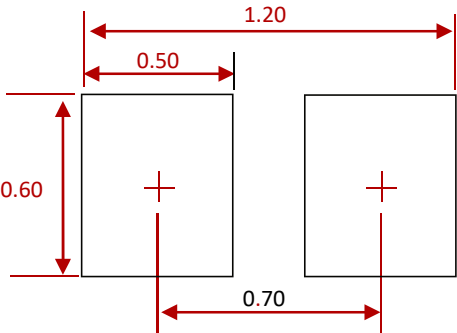


PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

Suggested Pad Layout



- NOTES:
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
MSESD10EMC24	DFN1006	10000

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